



FF784 - Sn/Pb SOLDER BALLS
FFG784 - Sn/Ag/Cu SOLDER BALLS

SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	2.45	\approx	2.86	
A ₁	0.40	0.50	0.60	
A ₂	0.65	\approx	0.95	
D/E	29.00 BASIC			
D ₁ /E ₁	27.00 REF			
e	1.00 BASIC			
phi b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
ccc	\approx	\approx	0.25	
ddd	\approx	\approx	0.25	
eee	\approx	\approx	0.10	
M	28			2

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAM-1

PK383_01_102210

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/24/09	1.0	Initial Xilinx release.
12/3/10	1.1	Changed maximum overall package thickness (symbol A) from 3.10 to 2.86.

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